


The amendments to claims 1 and 20 incorporate the limitations of claims 14 and 25 respectively. Claim 35 has been amended to address rejection under 35 USC 112. New claim 54 is previous claim 33 recast in independent form.

Applicants submit that the amendment to claim 35 places the claim in compliance with 35 USC 112, second paragraph.

In as much as the office action indicated claims 14, 25 and 33 as allowable if rewritten in independent form, applicants submit that the remaining claims are now patentable over the prior art of record.

For the above reasons, applicants submit that the application is now in condition for allowance. Such allowance is earnestly and respectfully solicited.

Respectfully submitted,  
Hormazdyar H. Dalal et al.

By   
Steven Capella, Attorney  
Reg. No. 33,086  
Telephone: 845-894-3669

**FAX RECEIVED**

NOV 25 2002

TECHNOLOGY CENTER 2800

### Amendments to the Claims

1 1. (4th amended) A package for containing electronic components, the  
 2 package comprising:  
 3 a first circuitized card;  
 4 a second circuitized card;  
 5 an interposer interposed between the first and second circuitized cards,  
 6 the interposer having an opening, the opening in the interposer and the first and  
 7 second circuitized card forming a cavity for containing at least one electronic  
 8 component  
 9 wherein the first circuitized card has a bottom surface and there is at least one  
 10 component mounted to the bottom surface, [and] wherein the interposer, first  
 11 circuitized card, and second circuitized card are circuitized multi-layer organic  
 12 laminate cards, wherein the first circuitized card and interposed are electrically  
and physically connected through a ball grid array and the interposer and the  
second circuitized card are electrically and physically connected through a ball  
grid array.

Cancel claims 6, 13, 14 .

1 20. (4th amended) A package for containing electronic components, the  
 2 package comprising:  
 3 a first circuitized card having a top and bottom surface;  
 4 a second circuitized card having a top and bottom surface;  
 5 an interposer having an opening, a top surface, and a bottom surface, the  
 6 interposer being electrically connected to the first circuitized card and the second  
 7 circuitized card through a first and second set of connections, the first set of  
 8 connections being interposed between the bottom surface of the first circuitized  
 9 card and the top surface of the interposer, the second set of connections being  
 10 interposed between the bottom surface of the interposer and the top surface of

11 the second circuitized card, wherein (a) the bottom surface of the second  
 12 circuitized card has a third set of connections for attaching the second circuitized  
 13 card to a system card, (b) the opening in the interposer, the bottom surface of  
 14 the first circuitized card, and the top surface of the second circuitized card form a  
 15 cavity for containing at least one electronic component, [and] (c) the interposer,  
 16 first circuitized card, and second circuitized card are circuitized multi-layer  
 17 organic laminate cards, and (d) each set of connections of the first, second and  
 18 third sets of connections is a ball grid array.

Cancel claims 24 and 25.

1 35. (amended) The package of claim 20 further comprising a third circuitized  
 2 card and a second interposer having a second opening, wherein the third  
 3 circuitized card, the second circuitized card, and the second opening in  
 4 the second interposer define a second cavity for containing at least one  
 5 electronic component, wherein the third circuitized card is electrically  
 6 connected to the second interposer through a fourth set of connections,  
 7 and wherein the second interposer is electrically connected to the second  
 8 circuitized card through a [fourth] fifth set of connections.

Add the following new claim.

1 54. (new) A package for containing electronic components, the package  
 2 comprising:  
 3 a first circuitized card having a top and bottom surface;  
 4 a second circuitized card having a top and bottom surface;  
 5 an interposer having an opening, a top surface, and a bottom surface, the  
 6 interposer being electrically connected to the first circuitized card and the second  
 7 circuitized card through a first and second set of connections, the first set of

8 connections being interposed between the bottom surface of the first circuitized  
 9 card and the top surface of the interposer, the second set of connections being  
 10 interposed between the bottom surface of the interposer and the top surface of  
 11 the second circuitized card, wherein (a) the bottom surface of the second  
 12 circuitized card has a third set of connections for attaching the second circuitized  
 13 card to a system card, (b) the opening in the interposer, the bottom surface of  
 14 the first circuitized card, and the top surface of the second circuitized card form a  
 15 cavity for containing at least one electronic component, (c) the interposer, first  
 16 circuitized card, and second circuitized card are circuitized multi-layer organic  
 17 laminate cards, and (d) said interposer has at least one electronic component on  
 18 its surface.

\*\*\*\*\*

**FAX RECEIVED**

NOV 25 2002

TECHNOLOGY CENTER 2800

FIS919980065US1

7

Appl. No. 09/158,616

NOV 25 '02 16:37 FR IPLM E FISHKILL 845 892 6363 TO 917038729318 P.10/10